

Vishay Siliconix

FREE

# P-Channel 100 V (D-S) 175 °C MOSFET

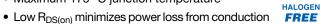


PRODUCT SUMMARY			
V <sub>DS</sub> (V)	-100		
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -10 \text{ V}$	0.0101		
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -4.5 \text{ V}$	0.0150		
Q <sub>g</sub> typ. (nC)	125		
I <sub>D</sub> (A)	-120		
Configuration	Single		

#### **FEATURES**

- TrenchFET® power MOSFET
- · Package with low thermal resistance

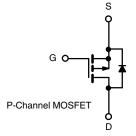




- · Compatible with logic-level gate driving
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

## **APPLICATIONS**

- Battery protection
- Motor drive control
- · Load switch



ORDERING INFORMATION	
Package	TO-263
Lead (Pb)-free and halogen-free	SUM70101EL-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25$	°C, unless otherw	rise noted)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	-100	V	
Gate-source voltage		V <sub>GS</sub>	± 20		
Continuous drain current <sup>d</sup>	T <sub>C</sub> = 25 °C	I <sub>D</sub>	-120		
$(T_J = 175  ^{\circ}C)$	T <sub>C</sub> = 125 °C		-78		
Pulsed drain current (100 μs)		I <sub>DM</sub>	-240	Α	
Avalanche current	L = 0.1 mH	I <sub>AS</sub>	-75	]	
Single pulse avalanche energy <sup>a</sup>	L = U.1 MH	E <sub>AS</sub>	281	mJ	
Power dissipation	$T_C = 25  ^{\circ}C  ^{\circ}$	- P <sub>D</sub>	375	W	
	T <sub>C</sub> = 125 °C b		125		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	UNIT	
Junction-to-ambient	PCB mount <sup>b</sup>	$R_{thJA}$	40	°C/W	
Junction-to-case		$R_{thJC}$	0.4	]	

#### **Notes**

- a. Duty cycle ≤ 1 %
- b. When mounted on 1" square PCB (FR4 material)
- c. See SOA curve for voltage derating
- d. Limited by package



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-100	-	-	V
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-1.5	-	-2.5	
Gate-body leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Zero gate voltage drain current		V <sub>DS</sub> = -100 V, V <sub>GS</sub> = 0 V	-	-	-1	
	I <sub>DSS</sub>	V <sub>DS</sub> = -100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	-50	μΑ
		V <sub>DS</sub> = -100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C	-	-	-250	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	-120	-	-	Α
Due in a summa and attack and interest 2	В	$V_{GS} = -10 \text{ V}, I_D = -30 \text{ A}$	-	0.0081	0.0101	Ω
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -20 A	-	0.0114	0.0150	
Forward transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = -15 V, I <sub>D</sub> = -25 A	-	60	-	S
Dynamic <sup>b</sup>						
Input capacitance	C <sub>iss</sub>		-	7000	-	pF
Output capacitance	Coss	$V_{GS} = 0 \text{ V}, V_{DS} = -50 \text{ V}, f = 1 \text{ MHz}$	1	2180	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	170	-	
Total gate charge <sup>c</sup>	Qg		-	125	190	
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = -50 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -110 \text{ A}$	-	29	-	nC
Gate-drain charge <sup>c</sup>	$Q_{gd}$		-	30	-	
Gate resistance	R <sub>g</sub>	f = 1 MHz	1.3	6.5	13	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD} = -50 \text{ V}, \text{ R}_L = 0.71 \Omega$ $I_D \cong -70 \text{ A},  V_{GEN} = -10 \text{ V}, \text{ R}_g = 1 \Omega$	1	20	30	
Rise time <sup>c</sup>	t <sub>r</sub>		-	40	60	no
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>		-	110	200	ns
Fall time <sup>c</sup>	t <sub>f</sub>		-	40	60	
<b>Drain-Source Body Diode Characte</b>	ristics (T <sub>C</sub> = 25	5 °C b)				
Continuous current	I <sub>S</sub>		1	-	-110	Α
Pulsed current	I <sub>SM</sub>		-	-	-240	A
Forward voltage <sup>a</sup>	V <sub>SD</sub>	$I_F = -85 \text{ A}, V_{GS} = 0 \text{ V}$	ì	-1	-1.5	V
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = -85 A, dl/dt = 100 A/μs	ì	110	170	ns
Peak reverse recovery charge	I <sub>RM(REC)</sub>		-	-7	-11	Α
Reverse recovery charge	Q <sub>rr</sub>		_	0.38	0.57	μC

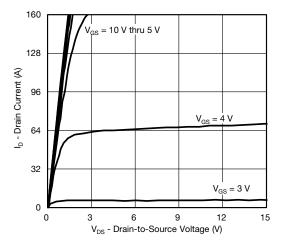
### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

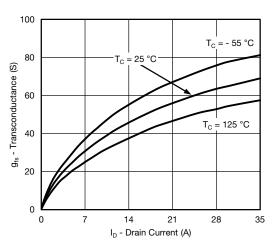
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



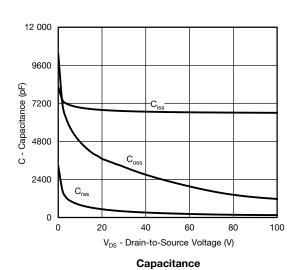
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

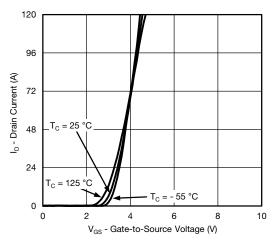


### **Output Characteristics**

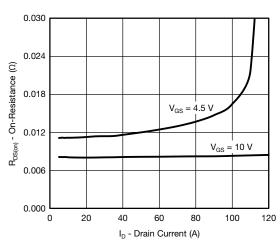


Transconductance

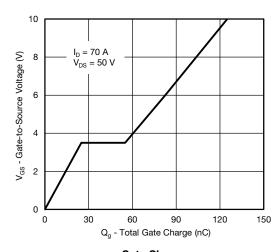




**Transfer Characteristics** 

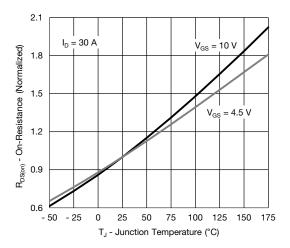


On-Resistance vs. Drain Current

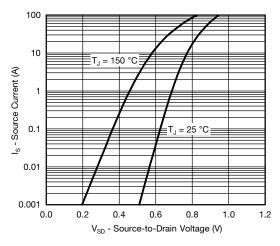




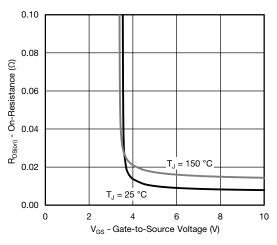
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



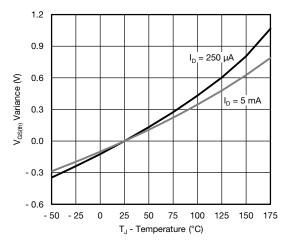
On-Resistance vs. Junction Temperature



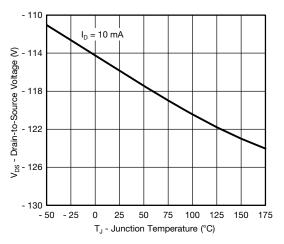
**Source Drain Diode Forward Voltage** 



On-Resistance vs. Gate-to-Source Voltage



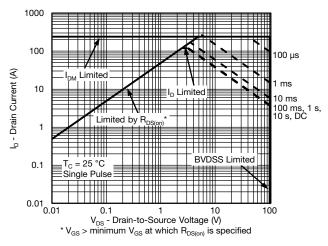
Threshold Voltage



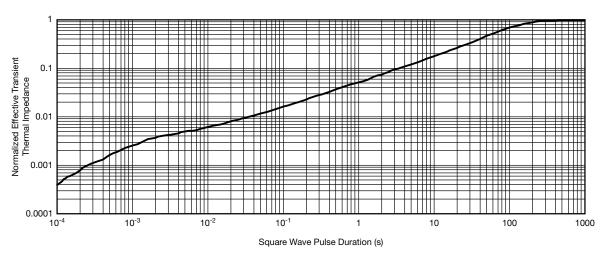
Drain Source Breakdown vs. Junction Temperature



# **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



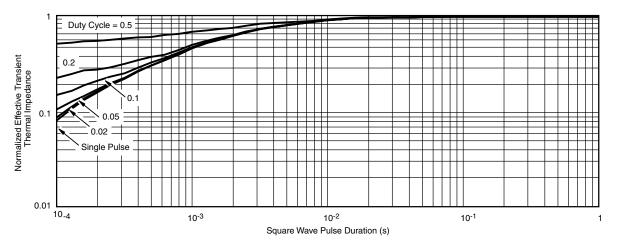
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

can widely vary depending on actual application parameters and operating conditions.

- Normalized Transient Thermal Impedance Junction to Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg277605">www.vishay.com/ppg277605</a>.



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